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PAD FUNCTIONS



The information given is believed to be correct at the time of issue.
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
 Back potential is the electrical potential of the substrate (bulk silicon) which does not require an electrical connection unless stated in this drawing.

Note: 1 mil = 0.001inch

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| <p><u>APPROVED</u></p> <p>GB</p> <p>.....</p> <p>DATE: 24.08.10</p> | <p style="text-align: center;">FDS8638</p> <p style="text-align: center;">FAIRCHILD SEMICONDUCTOR</p> | <p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 145 x 93 x 8</p> <p>BOND PADS (Mils): S = 139 x 41, G = 7 x 7</p> <p>MASK REF:</p> <p>GEOMETRY:</p> <p>BACK POTENTIAL: DRAIN</p> |
| <p><u>SERIAL NUMBER</u></p> <p>M000248</p> | | <p><u>METALLISATION</u></p> <p>TOP: Al</p> <p>BACK: Ti - NiV - Ag</p> |